AMPAK Technology Inc.

正基科技股份有限公司

SPECIFICATION

PRODUCT NAME：AP5812

REVISION：0.2(WEB)

DATE：Nov. 04th , 2026

Customer APPROVED	
Company	
Representative Signature	

PREPARED	REVIEW				APPROVED	DCC ISSUE
	PM	QA	ET			
			PE			
			ME			
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正基科技股份有限公司

AMPAK Technology Inc.

AP5812

Data Sheet

Address:
6F.-2, No. 23, Huanke 1st Rd., Zhubei City, Hsinchu County 302047, Taiwan
Website: http://www.ampak.com.tw/

Revision

Revision	Date	Description	Revised By
0.1	2026/08/27	-- Preliminary release	May
0.2	2026/11/04	Update Bluetooth Spec	May

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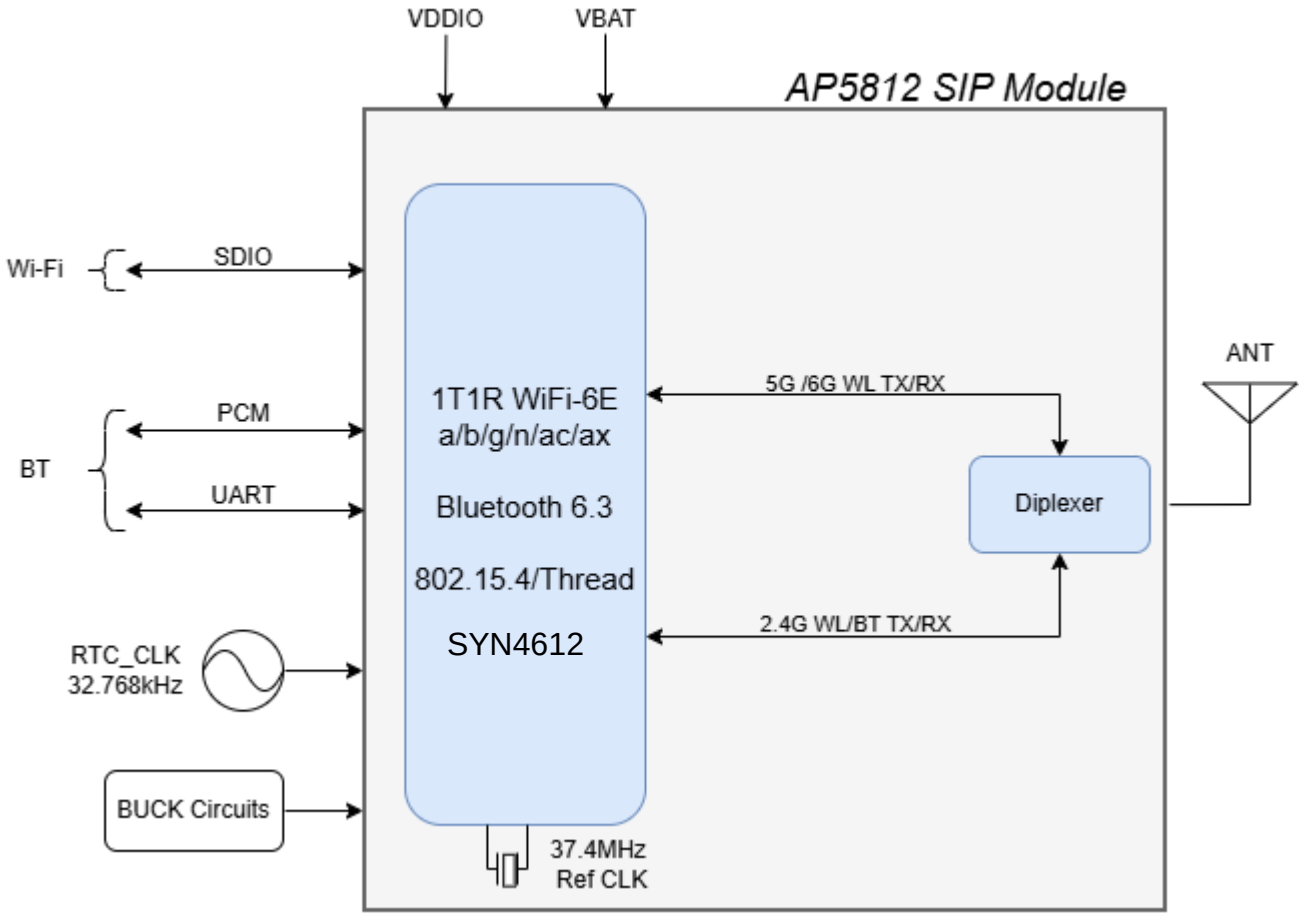
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1. Introduction

1.1 Overview

The AMPAK Technology® AP5812 is a fully Wi-Fi 6E and Bluetooth functionalities module with seamless roaming capabilities and advance security. It is capable of associating with variety of Wi-Fi 6E or legacy Access Points / Routers, AP5812 supports SDIO v3.0 / 2.0 interfaces by proper setting for Wi-Fi and UART/ PCM interface for Bluetooth.

In addition, this compact module is a total solution for a combination of Wi-Fi + Bluetooth technologies. The module is specifically developed for tablet, OTT box and portable & mobile devices.



1.2 Product Features

IEEE 802.11 Key Features

- IEEE802.11ax, 1x1 20MHz Tri band support WiFi6E 2.4G, 5G and 6GHz
- Single spatial stream with PHY rate up to 114.7 Mbps.
- 20MHz channels and up to 256-QAM support for 2.4GHz, 5GHz and 6GHz bands.
- Excellent sensitivity is achieved for both BT and Wi-Fi.
- Supports a standard SDIO v3.0 (4-bit and 1-bit) host interface that is backward compatible with SDIO v2.0.
- Full IEEE 802.11a/b/g/n/ac legacy protocols compatibility with enhanced performance.
- Client MU-MIMO support.
- Supported Partial RU(Resource Unit) in 802.11ax.
- Supported non-HT(802.11a) preamble in 6GHz.

Bluetooth Key Feature

- BT Core Specification Version 6.3, including the following support:
  Low energy (LE) isochronous channels
  LE power control
  LE enhanced connection update
  LE channel classification
  LE audio support
- Support for Advertising coding Scheme selection (Plan)
- Bluetooth Class 1 or Class 2 TX operation.
- AoA/AoD support.
- Supports extended synchronous connections (eSCO), for enhanced voice quality by allowing for retransmission of dropped packets.
- Supports multiple simultaneous Advanced Audio Distribution Profiles (A2DP) for stereo sound.
- Adaptive frequency hopping (AFH) to reduce radio frequency interference.
  Interface support: host controller interface (HCI) using a high-speed UART interface and PCM for audio data.
- Support for Bluetooth Channel Sounding

IEEE 802.15.4/Thread Key Feature

- Support for IEEE 802.15.4
- Supports Thread V1.3 and Zigbee 3.0 RCP model.

2. General Specification

2.1 General Specification

Model Name	AP5812
Product Description	1T1R 802.11 a/b/g/n/ac/ax Wi-Fi 6E + BT 6.3 + 802.15.4 Module
Dimension	W x L : 5.8x 6.9(typical) mm，H : 1.1 (Maximum) mm
Wi-Fi Interface	Support SDIO V3.0/ 2.0
BT Interface	UART / PCM
Operating temperature	-30°C to 85°C
Storage temperature	-40°C to 125°C
Humidity	Operating Humidity 10% to 95% Non-Condensing

Note: The optimal RF performance specified in the data sheet, however, is guaranteed only -10 °C to +55 °C and 3.2V < VBAT < 3.8V without derating performance.

2.2 DC Characteristics

2.2.1 Absolute Maximum Ratings

Symbol	Description	Min.	Max.	Unit
VBAT	Input supply Voltage	3.0	4.8	V
VDDIO	Digital/Bluetooth/SDIO/ I/O Voltage	1.62	1.98	V

Note : RF performance is optimal for 3.6V ≤ VBAT ≤ 4.8V. For 3.0V ≤VBAT ≤3.2V, device radios will operate but RF performance will degrade.

2.2.2 Recommended Operating Rating

The module requires two power supplies: VBAT and VDDIO.

Voltage rails	Min.	Typ.	Max.	Unit
VBAT	3.2	3.6	4.8	V
VDDIO	1.62	1.8	1.98	V

VBAT current consumption 1000mA (Peak), when VBAT = 3.6V

The module requires two power supplies: other Digital I/O Pins.

For VDDIO=1.8V	Min.	Max.	Unit
Input high voltage	0.65 x VDDIO	NA	V
Input low voltage	NA	0.35 x VDDIO	V
Output high voltage @ 2mA	VDDIO – 0.4	NA	V
Output low voltage @ 2mA	NA	0.4	V

3. Wi-Fi RF Specification

3.1 2.4GHz RF Specification

Conditions : VBAT=3.6V ; VDDIO=1.8V ; Temp=25°C

Feature	Description
WLAN Standard	IEEE 802.11 b/g/n/ax & Wi-Fi compliant
Frequency Range	2400 MHz ~ 2483.5 MHz (2.4GHz ISM Band)
Number of Channels	2400 MHz ~ 2483.5 MHz：Ch1 ~ Ch13
Modulation	802.11b : DQPSK、DBPSK、CCK 802.11g/n : OFDM /64-QAM、16-QAM、QPSK、BPSK 802.11ax : OFDMA /256-QAM、64-QAM、16-QAM、QPSK、BPSK
Resource Unit	Partial RU : BW20MHz : 26T、52T、106T、242T

Output Power, tolerance ± 2 dB

The transmit EVM quality & spectrum mask are compliant with IEEE 802.11 standard

802.11b	**1Mbps**	**2Mbps**	**5.5Mbps**	**11Mbps**	
	19	19	19	19	
802.11g	**6、9Mbps**	**12、18Mbps**	**24Mbps**	**36Mbps**	**48Mbps**
	19	19	18	18	17
	54Mbps				
	17				
802.11n 20MHz	**MCS0~2**	**MCS3**	**MCS4**	**MCS5**	**MCS6**
	18.5	18.5	18	17	16
	MCS7				
	16				
802.11ax 20MHz	**HE0~2**	**HE3**	**HE4**	**HE5**	**HE6**
	18.5	18.5	18	17	16
	HE7	**HE8**	**HE9**		
	16	15.5	15		

Note: The specifications of RF output power are subject to change to fulfill the safety regulation and requirements in end-user product.

Sensitivity, tolerance ± 2 dB

CCK modulation PER ≦ 8%、OFDM modulation PER ≦ 10%

802.11b	**Data Rate**	**Spec.(dBm)**		
	1Mbps	-98		

	2Mbps	-94		
	5.5Mbps	-92		
	11Mbps	-88		
802.11g	**Data Rate**	**Spec.(dBm)**	**Data Rate**	**Spec.(dBm)**
	6Mbps	-90	**24Mbps**	-82
	9Mbps	-88	**36Mbps**	-79
	12Mbps	-86	**48Mbps**	-76
	18Mbps	-84	**54Mbps**	-74
802.11n 20MHz	**Data Rate**	**Spec.(dBm)**	**Data Rate**	**Spec.(dBm)**
	MCS0	-91	**MCS4**	-78
	MCS1	-88	**MCS5**	-76
	MCS2	-85	**MCS6**	-75
	MCS3	-81	**MCS7**	-73
802.11ax 20MHz	**Data Rate**	**Spec.(dBm)**	**Data Rate**	**Spec.(dBm)**
	HE0	-92	**HE6**	-76
	HE1	-89	**HE7**	-74
	HE2	-86	**HE8**	-72
	HE3	-82	**HE9**	-70.5
	HE4	-79		
	HE5	-77		
Maximum Input Level	802.11b: -10 dBm			
	802.11g/n/ax: -20 dBm			

3.2 5 GHz RF Specification

Conditions : VBAT=3.6V ; VDDIO=1.8V ; Temp=25°C

Feature	Description
WLAN Standard	IEEE 802.11a/n/ac/ax & Wi-Fi compliant
Frequency Range	5150~5350MHz、5470~5725MHz、5745~5850MHz (5GHz UNII Band)
Number of Channels	5150~5350MHz：Ch36 ~ Ch64 5470~5725MHz：Ch100 ~ Ch144 5745~5850MHz：Ch149 ~ Ch165
Modulation	802.11a : OFDM /64-QAM、16-QAM、QPSK、BPSK 802.11n : OFDM /64-QAM、16-QAM、QPSK、BPSK 802.11ac : OFDM /256-QAM、64-QAM、16-QAM、QPSK、BPSK 802.11ax : OFDMA /1024-QAM、256-QAM、64-QAM、16-QAM、QPSK、BPSK
Resource Unit	Partial RU : BW20MHz : 26T、52T、106T、242T

Output Power, tolerance ± 2 dB

The transmit EVM quality & spectrum mask are compliant with IEEE 802.11 standard

802.11a	**Frequency (MHz)**	**6~9Mbps**	**12~18Mbps**	**24Mbps**	**36Mbps**
	5150~5350	15	15	15	15
	5470~5725	15	15	15	15
	5745~5850	15	15	15	15
	Frequency (MHz)	**48Mbps**	**54Mbps**		
	5150~5350	15	14.5		
	5470~5725	15	14.5		
	5745~5850	15	14.5		
802.11n 20MHz	**Frequency (MHz)**	**MCS0~2**	**MCS3**	**MCS4**	**MCS5**
	5150~5350	14.5	14.5	14.5	14.5
	5470~5725	14.5	14.5	14.5	14.5
	5745~5850	14.5	14.5	14.5	14.5
	Frequency (MHz)	**MCS6**	**MCS7**		
	5150~5350	14.5	13.5		
	5470~5725	14.5	13.5		
	5745~5850	14.5	13.5		

802.11ac 20MHz	Frequency (MHz)	MCS0~2	MCS3	MCS4	MCS5
	5150~5350	14.5	14.5	14.5	14.5
	5470~5725	14.5	14.5	14.5	14.5
	5745~5850	14.5	14.5	14.5	14.5
	Frequency (MHz)	MCS6	MCS7	MCS8	
	5150~5350	14.5	13.5	12	
	5470~5725	14.5	13.5	12	
	5745~5850	14.5	13.5	12	
802.11ax 20MHz	Frequency (MHz)	HE0~2	HE3	HE4	HE5
	5150~5350	14.5	14.5	14.5	14.5
	5470~5725	14.5	14.5	14.5	14.5
	5745~5850	14.5	14.5	14.5	14.5
	Frequency (MHz)	HE6	HE7	HE8	HE9
	5150~5350	14.5	13.5	12	11
	5470~5725	14.5	13.5	12	11
	5745~5850	14.5	13.5	12	11

Note: The specifications of RF output power are subject to change to fulfill the safety regulation and requirements in end-user product.

Sensitivity, tolerance ± 2 dB

CCK modulation PER ≦ 8%、OFDM modulation PER ≦ 10%

802.11a	Data Rate	Spec.(dBm)	Data Rate	Spec.(dBm)
	6Mbps	-90	24Mbps	-83
	9Mbps	-89	36Mbps	-79
	12Mbps	-88	48Mbps	-74
	18Mbps	-86	54Mbps	-73
802.11n 20MHz	Data Rate	Spec.(dBm)	Data Rate	Spec.(dBm)
	MCS0	-90	MCS4	-79
	MCS1	-88	MCS5	-75
	MCS2	-86	MCS6	-72
	MCS3	-83	MCS7	-71
802.11ac 20MHz	Data Rate	Spec.(dBm)	Data Rate	Spec.(dBm)
	MCS0	-90	MCS5	-75

	MCS1	-88	**MCS6**	-72
	MCS2	-86	**MCS7**	-71
	MCS3	-83	**MCS8**	-67
	MCS4	-79		
802.11ax 20MHz	**Data Rate**	**Spec.(dBm)**	**Data Rate**	**Spec.(dBm)**
	HE0	-90	**HE6**	-72
	HE1	-88	**HE7**	-71
	HE2	-86	**HE8**	-67
	HE3	-83	**HE9**	-64
	HE4	-79		
	HE5	-75		
Maximum Input Level	802.11a/n/ac/ax: -30 dBm			

3.3 6GHz RF Specification

Conditions : VBAT=3.6V ; VDDIO=1.8V ; Temp=25°C

Feature	**Description**
WLAN Standard	IEEE 802.11ax & Wi-Fi compliant Non-HT(802.11a) preamble for ack/beacon
Frequency Range	5925~7125MHz (6GHz U-NII5, U-NII6, U-NII-7, U-NII-8 Band)
Number of Channels	5925~6425MHz：6G1 ~ 6G93 6425~6525MHz：6G97 ~ 6G113 6525~6875MHz：6G117~6G181 6875~7125MHz：6G185~6G233
Modulation	802.11ax : OFDMA /1024-QAM、256-QAM、64-QAM、16-QAM、QPSK、BPSK
Resource Unit	Partial RU : BW20MHz : 26T、52T、106T、242T

Output Power , tolerance ± 2.5 dB

The transmit EVM quality & spectrum mask are compliant with IEEE 802.11 standard

802.11ax 20MHz	**Frequency (MHz)**	**HE0~2**	**HE3**	**HE4**	**HE5**
	5925~6425	12	12	12	12
	6425~6525	12	12	12	12
	6535~6675	12	12	12	12
	6695~7125	12	12	12	12
	Frequency (MHz)	**HE6**	**HE7**	**HE8**	**HE9**

	5925~6425	11	10	9	8
	6425~6525	11	10	9	8
	6535~6675	11	10	9	8
	6695~7125	11	10	9	8

Note: The specifications of RF output power are subject to change to fulfill the safety regulation and requirements in end-user product.

Sensitivity, tolerance ± 2 dB, OFDM modulation PER ≦ 10%

802.11ax 20MHz	**Frequency (MHz)**	**Data Rate**	**Spec.(dBm)**	**Data Rate**	**Spec.(dBm)**
	5925~6425	**HE0**	-89	**HE5**	-74
		HE1	-86	**HE6**	-71
		HE2	-84	**HE7**	-68
		HE3	-83	**HE8**	-66
		HE4	-77	**HE9**	-63
	Frequency (MHz)	**Data Rate**	**Spec.(dBm)**	**Data Rate**	**Spec.(dBm)**
	6425~6525	**HE0**	-89	**HE5**	-74
		HE1	-86	**HE6**	-71
		HE2	-84	**HE7**	-68
		HE3	-83	**HE8**	-66
		HE4	-77	**HE9**	-63
	Frequency (MHz)	**Data Rate**	**Spec.(dBm)**	**Data Rate**	**Spec.(dBm)**
	6525~6875	**HE0**	-89	**HE5**	-74
		HE1	-86	**HE6**	-71
		HE2	-84	**HE7**	-68
		HE3	-83	**HE8**	-66
		HE4	-77	**HE9**	-63
	Frequency (MHz)	**Data Rate**	**Spec.(dBm)**	**Data Rate**	**Spec.(dBm)**
	6875~7125	**HE0**	-86	**HE5**	-70
		HE1	-82	**HE6**	-67
		HE2	-80	**HE7**	-64
		HE3	-79	**HE8**	-62
		HE4	-73	**HE9**	-59

4. Bluetooth Specification

4.1 Bluetooth Specification

Conditions : VBAT=3.6V ; VDDIO=1.8V ; Temp=25°C

Feature	Description
General Specification	
Bluetooth Standard	BDR、EDR(1Mbps & 2Mbps)、LE(1Mbps)、2LE(2Mbps) LELR(125Kbps)、LELR(500Kbps)
Host Interface	UART
Frequency Band	2402 MHz ~ 2480 MHz
Number of Channels	79 channels for classic、40 channels for BLE
Modulation	GFSK, π/4-DQPSK, 8DPSK
RF Specification	
Output Power, tolerance ± 2.5 dB	
	CL1 (dBm)
BDR Output Power	7
EDR Output Power	6
BLE Output Power	7
Sensitivity, tolerance ± 2.5 dB	
Sensitivity @ BER=0.1% for GFSK (1Mbps)	-87 dBm
Sensitivity @ BER=0.01% for π/4-DQPSK (2Mbps)	-89 dBm
Sensitivity @ BER=0.01% for 8DPSK (3Mbps)	-84 dBm
Sensitivity @ PER=30.8% for LE (1Mbps)	-90 dBm
Sensitivity @ PER=30.8% for 2LE (2Mbps)	-90 dBm
Sensitivity @ PER=30.8% for LELR (125Kbps)	-100 dBm
Sensitivity @ PER=30.8% for LELR (500Kbps)	-95 dBm

Maximum Input Level	GFSK (1Mbps):-20dBm
	π/4-DQPSK (2Mbps) :-20dBm
	8DPSK (3Mbps) :-20dBm

Note*：The Bluetooth BDR output power is able to be configured by firmware (hcd file).

5. 802.15.4 Specification

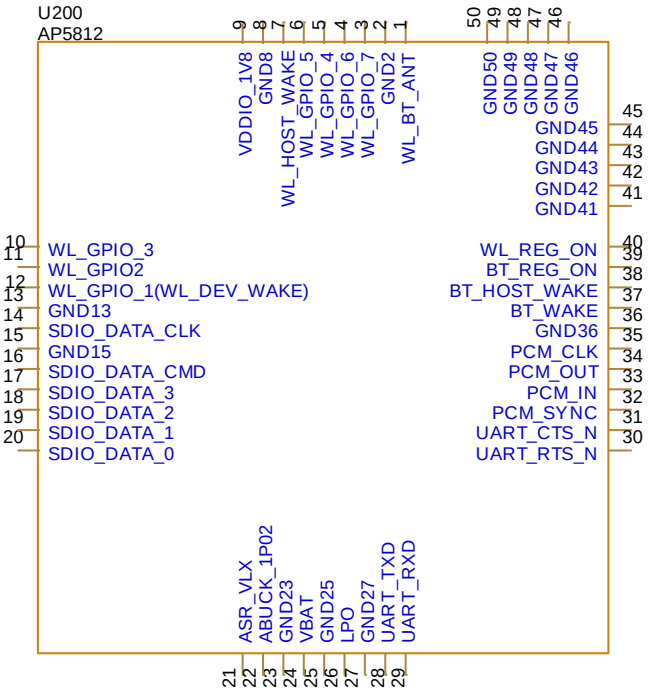
5.1 802.15.4 Specification

Conditions : VBAT=3.6V ; VDDIO=1.8V ; Temp:25°C

Feature	**Description**
General Specification	
802.15.4 Standard	250 kbps
Host Interface	UART
Frequency Band	2400 MHz ~ 2480 MHz
Number of Channels	16 channels
Modulation	O-QPSK
RF Specification	
TX Output Power , tolerance ± 2 dBm	
POWER_AVERAGE	8 dBm
EVM_ALL	< 35%
FREQ_ERROR_AVG_PPM	± 40ppm
SYMBOL_CLK_ERR	± 40ppm
RX	
Sensitivity	-90 dBm

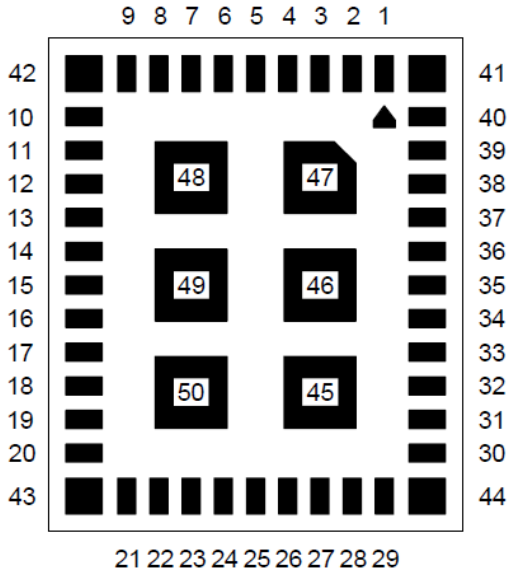
6. Pin Definition

6.1 Pin Outline



PIN OUTLINE

<TOP VIEW>



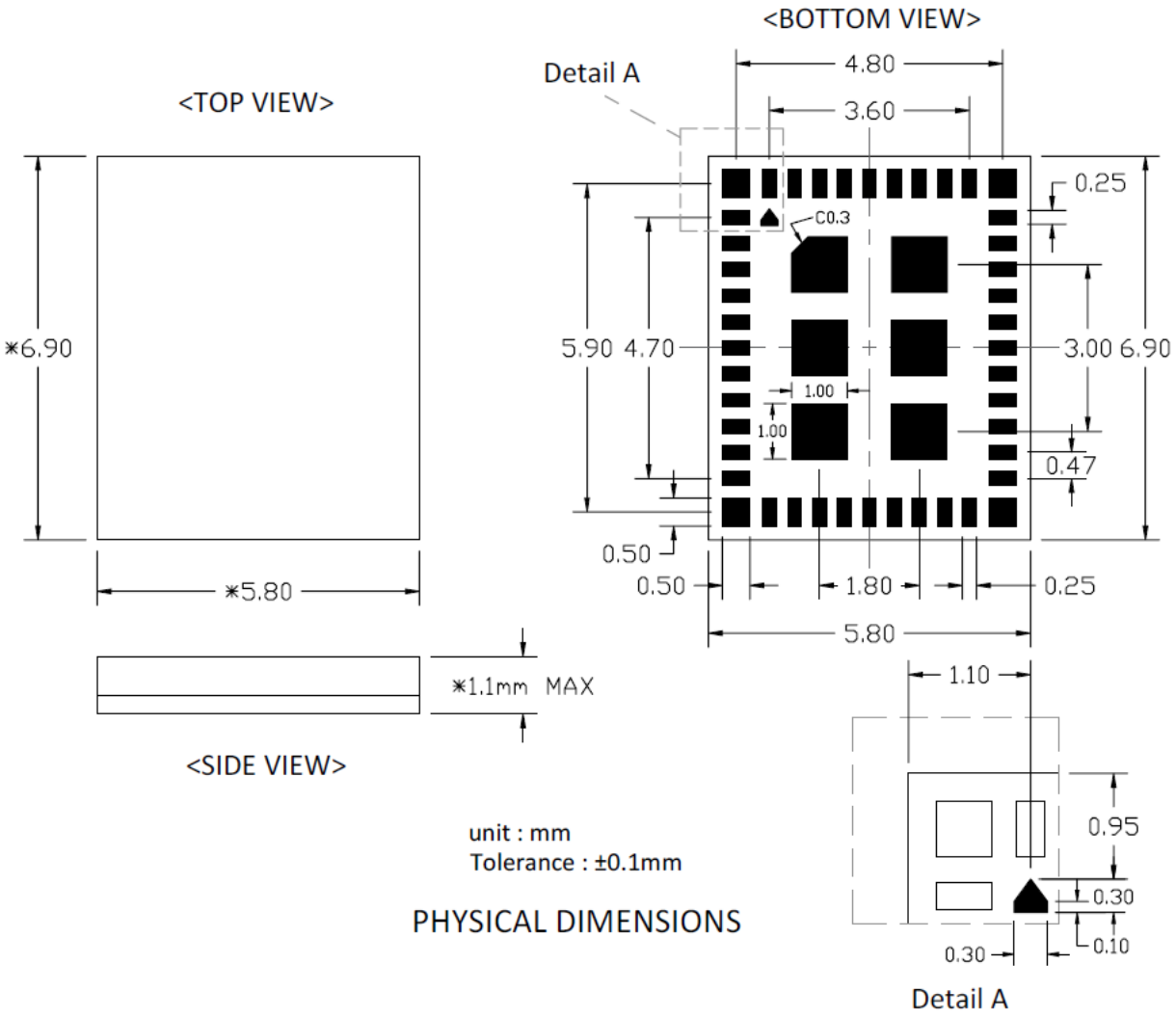
6.2 Pin Assignment

NO	Name	Type	Description
1	WL_BT_ANT	I/O	RF I/O port
2	GND	—	Ground connections
3	WL_GPIO_7	I/O	This pin can be programmed to be a GPIO7
4	WL_GPIO_6	I/O	This pin can be programmed to be a GPIO6
5	WL_GPIO_4	I/O	This pin can be programmed to be a GPIO4
6	WL_GPIO_5	I/O	This pin can be programmed to be a GPIO5
7	WL_HOST_WAKE	O	WLAN to wake-up HOST
8	GND	—	Ground connections
9	VDDIO_1V8	P	I/O Voltage1.8V supply input
10	WL_GPIO_3	I/O	This pin can be programmed to be a GPIO3
11	WL_GPIO_2	I/O	This pin can be programmed to be a GPIO2
12	WL_GPIO_1	I/O	This pin can be programmed to be a GPIO1 (WL_DEV_WAKE(I))
13	GND	—	Ground connections
14	SDIO_DATA_CLK	I/O	SDIO clock line
15	GND	—	Ground connections
16	SDIO_DATA_CMD	I/O	SDIO command line
17	SDIO_DATA_3	I/O	SDIO data line 3
18	SDIO_DATA_2	I/O	SDIO data line 2
19	SDIO_DATA_1	I/O	SDIO data line 1
20	SDIO_DATA_0	I/O	SDIO data line 0
21	ASR_VLX	O	Internal Analog Buck voltage generation pin
22	ABUCK_1P12	I	Internal Analog Buck voltage generation pin
23	GND	—	Ground connections
24	VBAT	P	Main power voltage source input
25	GND	—	Ground connections
26	LPO	I	External Low Power Clock input (32.768KHz)
27	GND	—	Ground connections
28	UART_TXD	O	Bluetooth UART interface
29	UART_RXD	I	Bluetooth UART interface
30	UART_RTS_N	O	Bluetooth UART interface
31	UART_CTS_N	I	Bluetooth UART interface
32	PCM_SYNC	I/O	PCM sync signal

33	PCM_IN	I	PCM data input
34	PCM_OUT	O	PCM Data output
35	PCM_CLK	I/O	PCM clock
36	GND	—	Ground connections
37	BT_WAKE	I	HOST wake-up Bluetooth device
38	BT_HOST_WAKE	O	Bluetooth device to wake-up HOST
39	BT_REG_ON	I	Power up/down internal regulators used by BT section
40	WL_REG_ON	I	Power up/down internal regulators used by WiFi section
41	GND	—	Ground connections
42	GND	—	Ground connections
43	GND	—	Ground connections
44	GND	—	Ground connections
45	GND	—	Ground connections
46	GND	—	Ground connections
47	GND	—	Ground connections
48	GND	—	Ground connections
49	GND	—	Ground connections
50	GND	—	Ground connections

7. Dimensions

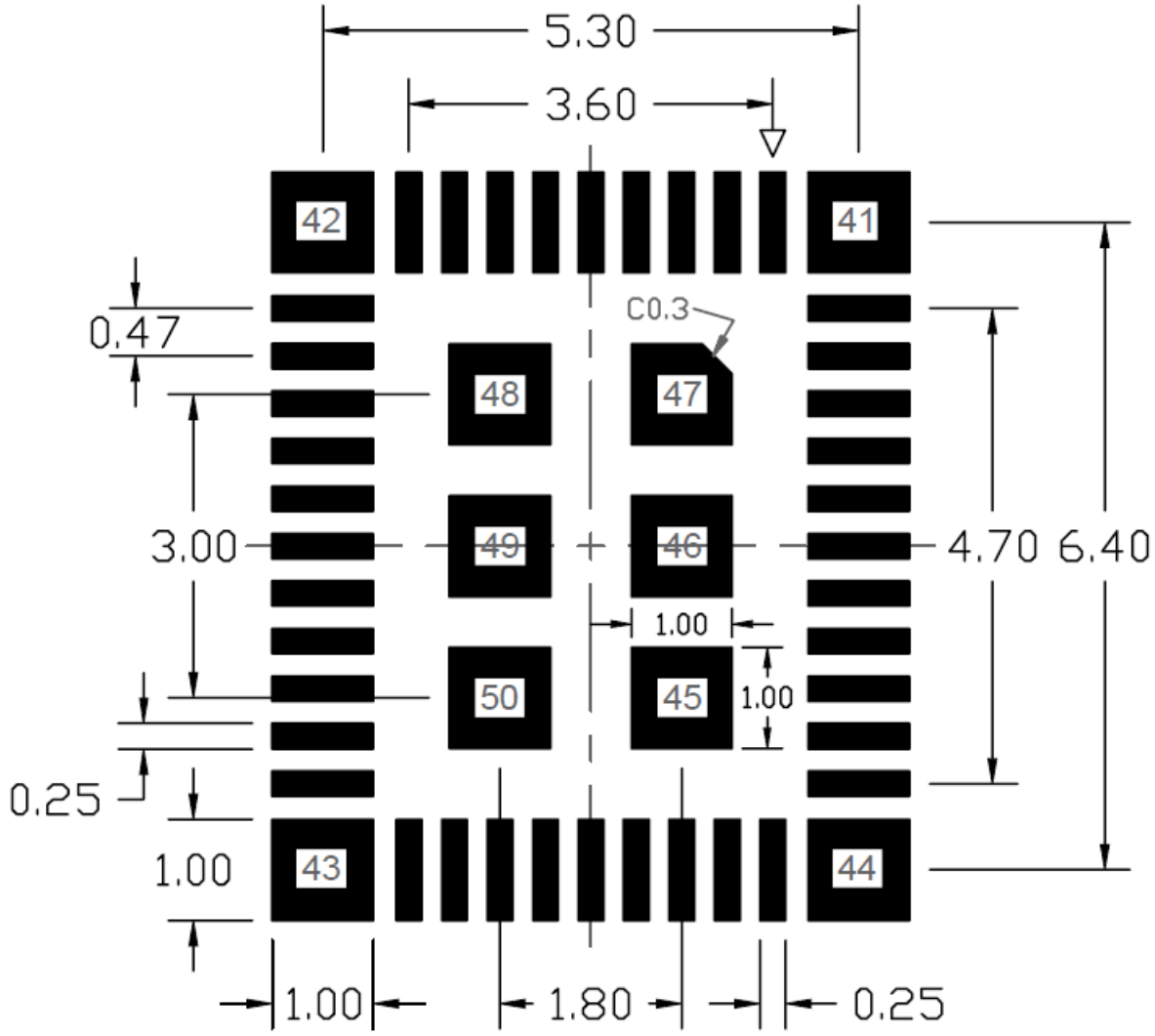
7.1 Module Dimensions



7.2 Recommended footprint

RECOMMENDED FOOTPRINT

<TOP VIEW>



unit : mm
Tolerance : ±0.1mm

- Solder paste layer design is generally the same as recommended footprint.

1. If soldering quality with good wetting on upright side is essential for PQC, how to optimize the aperture design in the stencil to adjust the amount of solder paste would be crucial.
   In addition, a kind of stencil design with stepped thickness in partial area would be considered if the thickness of stencil is about 0.1mm or thinner. Please optimize the stencil design by manufacture engineer or contact AMPAK FAE for assistance.

7.3 External clock reference

External LPO signal characteristics

Parameter	Specification	Units
Nominal input frequency	32.768	kHz
Frequency accuracy	+/-25	ppm
Duty cycle	30 - 70	%
Input signal amplitude	1.8±0.09	V
Signal type	Square-wave or sine-wave	-
Input impedance	>100k <5	Ω pF
Clock jitter (integrated over 300Hz – 15KHz)	<1	Hz
Output high voltage	0.7Vio - Vio	V

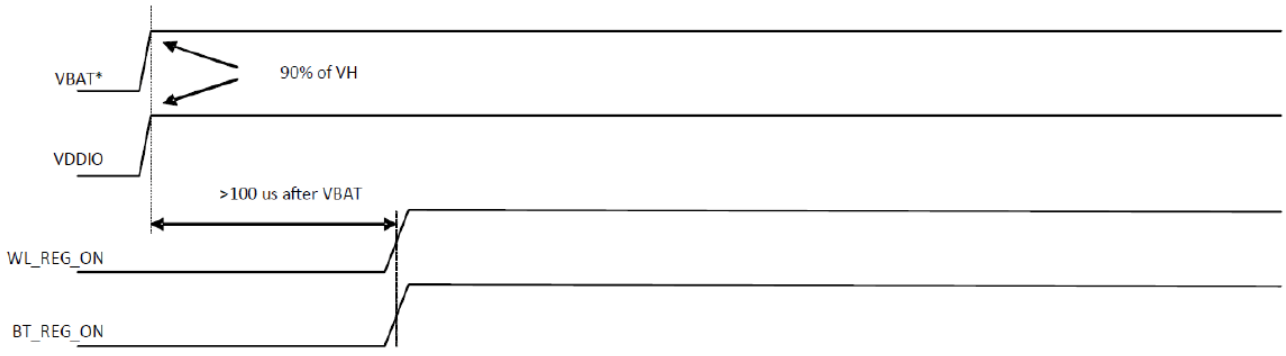
8. Host Interface Timing Diagram

8.1 Power-up Sequence Timing Diagram

The module has signals that allow the host to control power consumption by enabling or disabling the Bluetooth, WLAN and internal regulator blocks. These signals are described below.

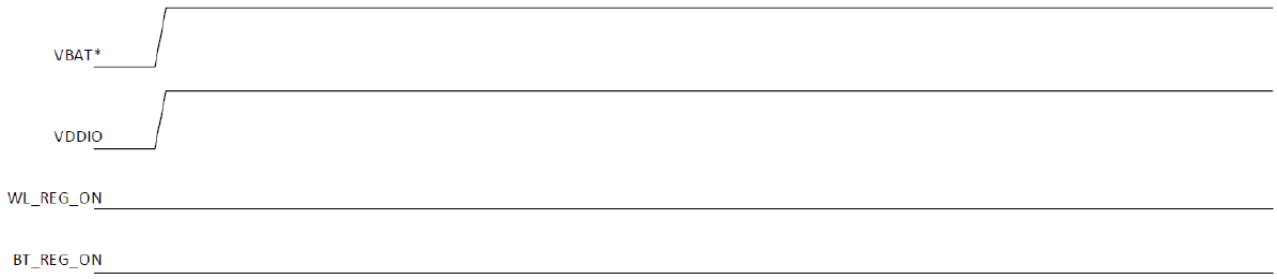
Additionally, diagrams are provided to indicate proper sequencing of the signals for carious operating states. The timing value indicated are minimum required values: longer delays are also acceptable.

- WL_REG_ON: Used by the PMU to power up or power down the internal regulators used by the WLAN section. When this pin is high, the regulators are enabled and the WLAN section is out of reset. When this pin is low the WLAN section is in reset.
- BT_REG_ON: Used by the PMU to power up or power down the internal regulators used by the BT section. Low asserting reset for Bluetooth. This pin has no effect on WLAN and does not control any PMU functions. This pin must be driven high or low (not left floating).



*Notes:
1. The VBAT and VDDIO 10%–90% rise-time slopes must be greater than 50 microseconds/V.
2. VBAT should be up before or at the same time as VDDIO . VDDIO should NOT be present first or be held high before VBAT is high .

WLAN=ON, Bluetooth=ON



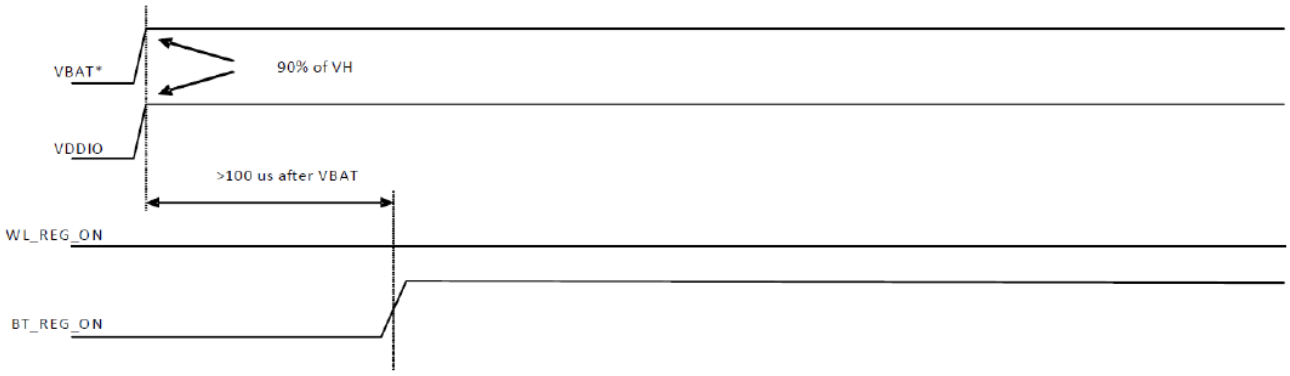
*Notes:
1. The VBAT and VDDIO 10%–90% rise-time slopes must be greater than 50 microseconds/V.
2. VBAT should be up before or at the same time as VDDIO. VDDIO should NOT be present first or be held high before VBAT is high.

WLAN=OFF, Bluetooth=OFF



***Notes:**
1. The VBAT and VDDIO 10%–90% rise-time slopes must be greater than 50 microseconds/V.
2. VBAT should be up before or at the same time as VDDIO. VDDIO should NOT be present first or be held high before VBAT is high.

WLAN=ON, Bluetooth=OFF



WLAN=OFF, Bluetooth=ON

8.2 SDIO Interface Description

The AP5812 support for SDIO 3.0 at 1.8V signaling, including the new UHS-I modes:
Default speed up to 25 MHz, including 1- and 4-bit modes.

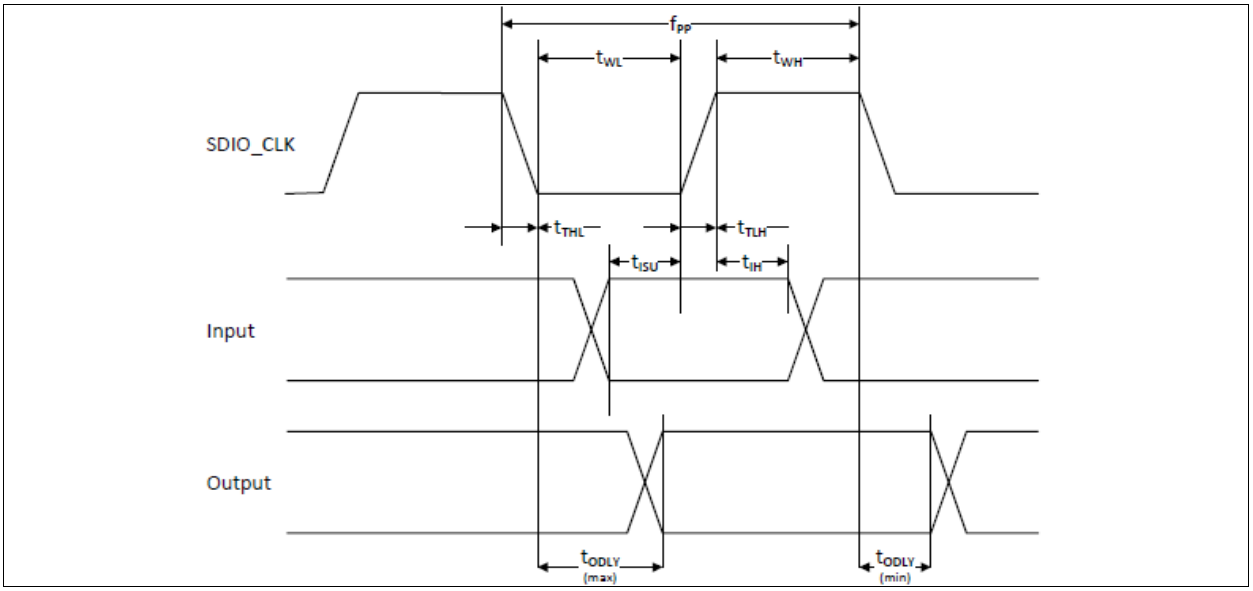
- SDR12: SDR up to 25 MHz.
- SDR25: SDR up to 50 MHz.
- SDR50: SDR up to 100 MHz.
- SDR104: SDR up to 150 MHz.
- DDR50: DDR up to 50 MHz.

Note: The AP5812 is backward compatible with SDIO v2.0 host interfaces.
The SDIO interface also can map the interrupt signal to a GPIO pin for applications requiring an interrupt different from the one provided by the SDIO interface. The ability to force control of the gated clocks from within the device is also provided. SDIO mode is enabled by strapping options.

SDIO Pin Description

SD 4-Bit Mode	
DATA0	Data Line 0
DATA1	Data Line 1 or Interrupt
DATA2	Data Line 2 or Read Wait
DATA3	Data Line 3
CLK	Clock
CMD	Command Line

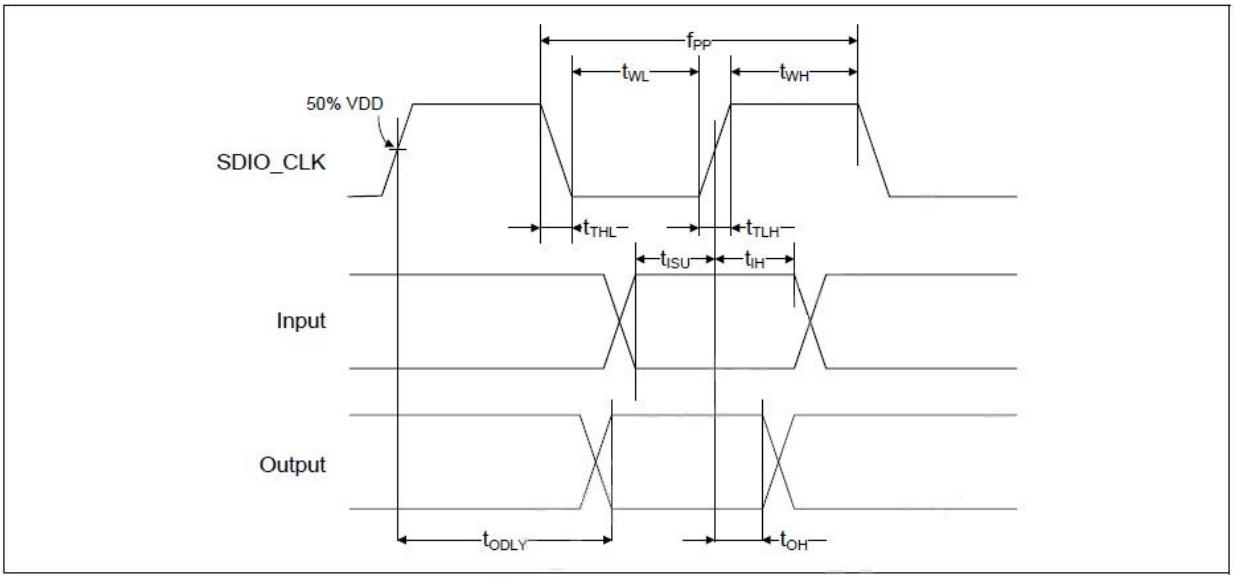
SDIO Default Mode Timing Diagram



Parameter	*Symbol*	*Minimum*	*Typical*	*Maximum*	*Unit*
SDIO CLK (All values are referred to minimum VIH and maximum VIL[b])					
Frequency – Data Transfer mode	fPP	0	–	25	MHz
Frequency – Identification mode	fOD	0	–	400	kHz
Clock low time	tWL	10	–	–	ns
Clock high time	tWH	10	–	–	ns
Clock rise time	tTLH	–	–	10	ns
Clock low time	tTHL	–	–	10	ns
Inputs: CMD, DAT (referenced to CLK)					
Input setup time	tISU	5	–	–	ns
Input hold time	tIH	5	–	–	ns
Outputs: CMD, DAT (referenced to CLK)					
Output delay time – Data Transfer mode	tODLY	0	–	14	ns
Output delay time – Identification mode	tODLY	0	–	50	ns

a. Timing is based on CL ≤ 40pF load on CMD and Data.
b. min(Vih) = 0.7 × VDDIO and max(Vil) = 0.2 × VDDIO.

SDIO High Speed Mode Timing Diagram

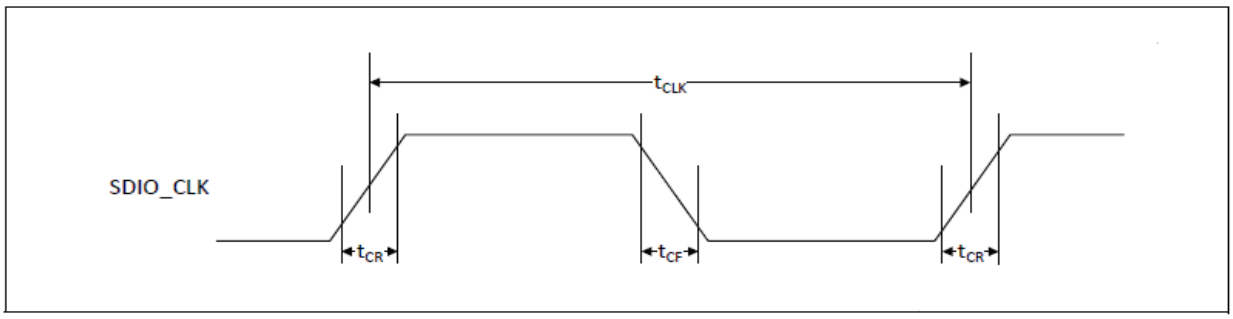


Parameter	Symbol	Minimum	Typical	Maximum	Unit
SDIO CLK (all values are referred to minimum VIH and maximum VIL[b])					
Frequency – Data Transfer Mode	fPP	0	–	50	MHz
Frequency – Identification Mode	fOD	0	–	400	kHz
Clock low time	tWL	7	–	–	ns
Clock high time	tWH	7	–	–	ns
Clock rise time	tTLH	–	–	3	ns
Clock low time	tTHL	–	–	3	ns
Inputs: CMD, DAT (referenced to CLK)					
Input setup Time	tISU	6	–	–	ns
Input hold Time	tIH	2	–	–	ns
Outputs: CMD, DAT (referenced to CLK)					
Output delay time – Data Transfer Mode	tODLY	–	–	14	ns
Output hold time	tOH	2.5	–	–	ns
Total system capacitance (each line)	CL	–	–	40	pF

a. Timing is based on CL ≤ 40 pF load on CMD and Data.
b. min(Vih) = 0.7 × VDDIO and max(Vil) = 0.2 × VDDIO.

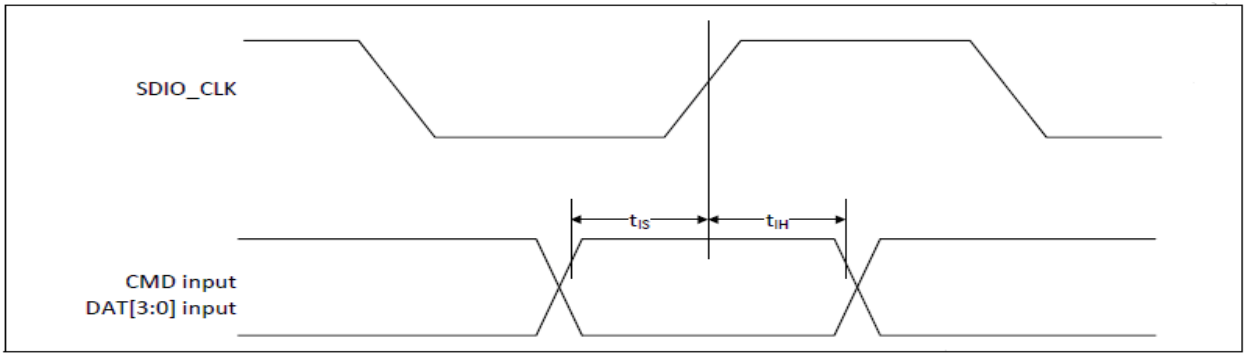
SDIO Bus Timing Specifications in SDR Modes

Clock timing (SDR Modes)



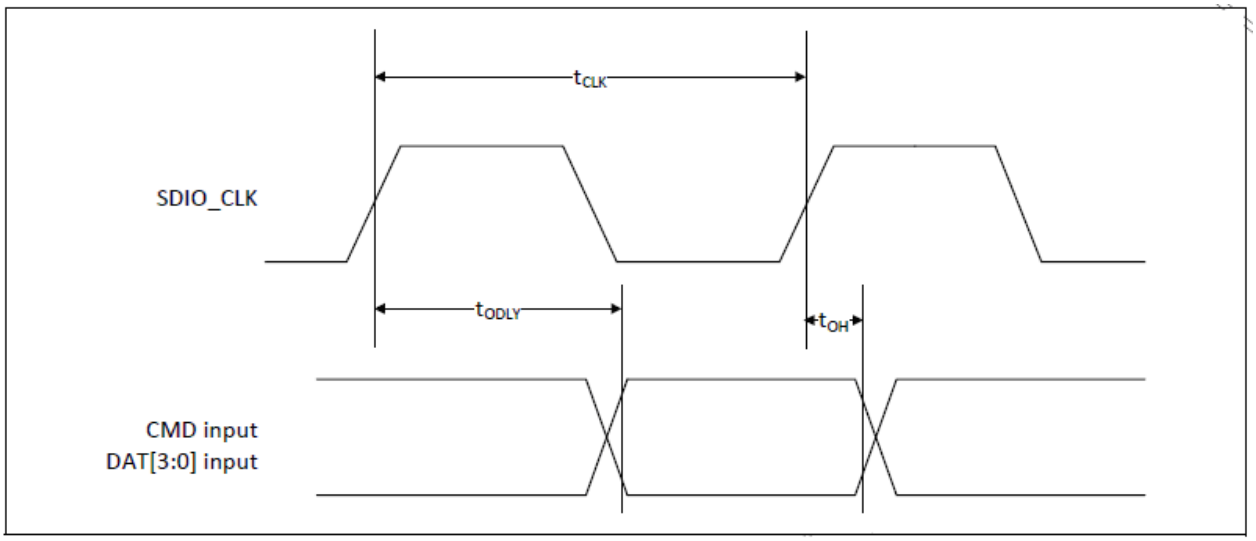
Parameter	Symbol	Minimum	Maximum	Unit	Comments
–	t_{CLK}	40	–	ns	SDR12 mode
		20	–	ns	SDR25 mode
		10	–	ns	SDR50 mode
		4.8	–	ns	SDR104 mode
–	t_{CR}, t_{CF}	–	0.2 × t_{CLK}	ns	t_{CR}, t_{CF} < 2.00 ns (max) @100 MHz, C_{CARD} = 10 pF t_{CR}, t_{CF} < 0.96 ns (max) @208 MHz, C_{CARD} = 10 pF
Clock duty	–	30	70	%	–

SDIO Bus Input timing (SDR Modes)



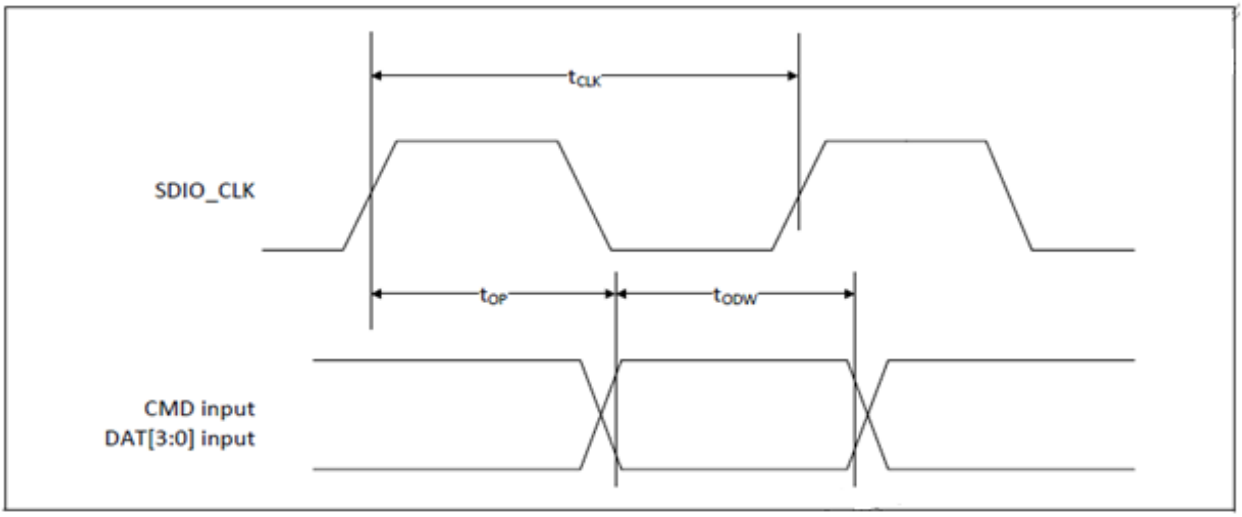
Symbol	Minimum	Maximum	Unit	Comments
SDR104 Mode				
t_{IS}	1.4	–	ns	C_{CARD} = 10 pF, VCT = 0.975V
t_{IH}	0.80	–	ns	C_{CARD} = 5 pF, VCT = 0.975V
SDR50 Mode				
t_{IS}	3.00	–	ns	C_{CARD} = 10 pF, VCT = 0.975V
t_{IH}	0.80	–	ns	C_{CARD} = 5 pF, VCT = 0.975V

SDIO Bus output timing (SDR Modes up to 100MHz)



Symbol	Minimum	Maximum	Unit	Comments
t_{ODLY}	–	7.5	ns	t_{CLK} ≥ 10 ns C_L = 30 pF using driver type B for SDR50
t_{ODLY}	–	14.0	ns	t_{CLK} ≥ 20 ns C_L = 40 pF using for SDR12, SDR25
t_{OH}	1.5	–	ns	Hold time at the t_{ODLY} (min) C_L = 15 pF

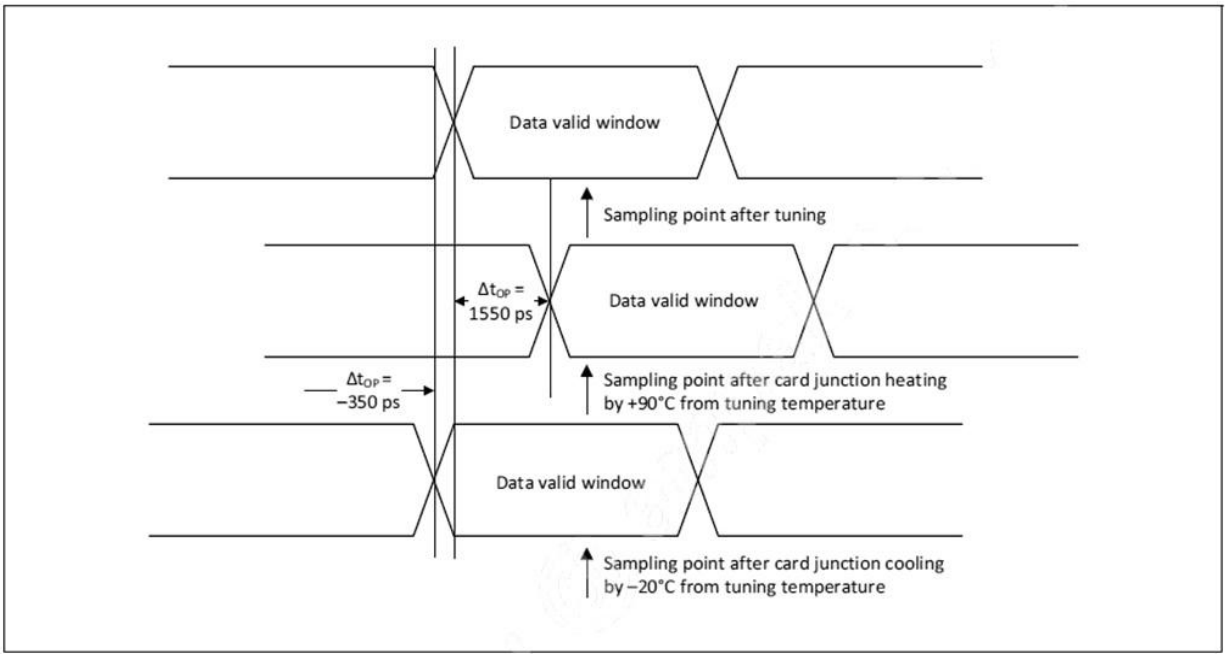
Card output timing (SDR Modes 100MHz to 208MHz)



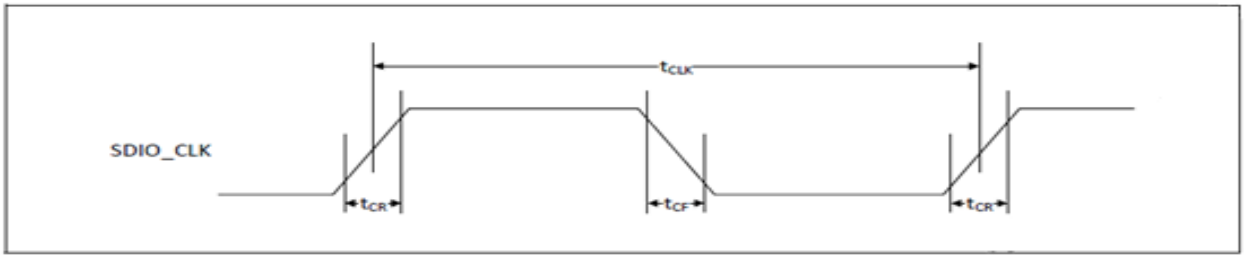
Symbol	Minimum	Maximum	Unit	Comments
t_{OP}	0	2	UI	Card output phase
Δt_{OP}	–350	+1550	ps	Delay variation due to temp change after tuning
t_{ODW}	0.60	–	UI	t_{ODW}=2.88 ns @208 MHz

- Δt_{OP} = +1550 ps for junction temperature of Δt_{OP} = 90 degrees during operation
- Δt_{OP} = –350 ps for junction temperature of Δt_{OP} = –20 degrees during operation
- Δt_{OP} = +2600 ps for junction temperature of Δt_{OP} = –20 to +125 degrees during operation

Δt_{OP} Consideration for Variable Data Window (SDR 104 Mode)

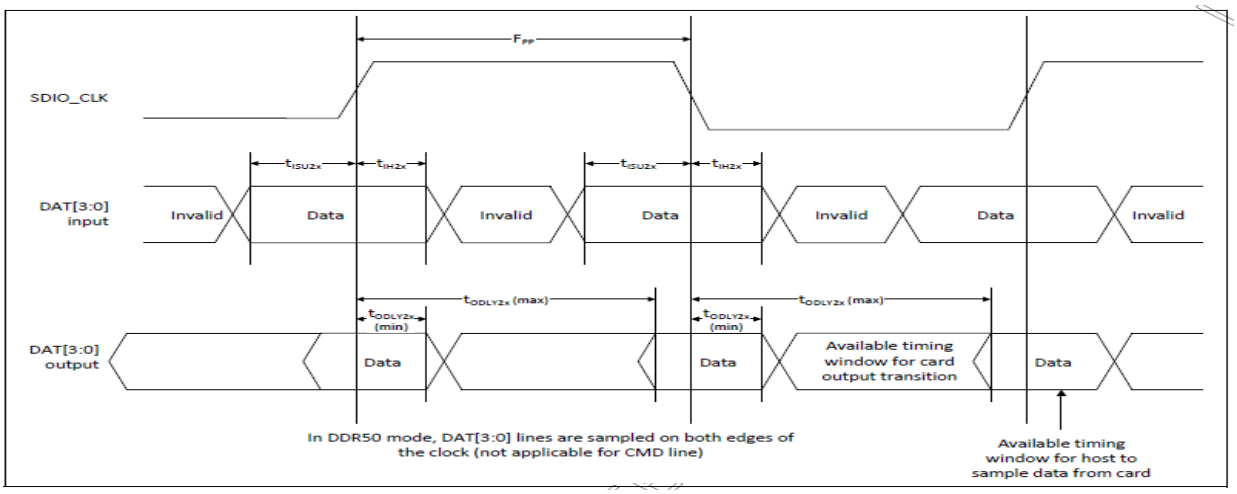


SDIO Bus Timing Specifications in DDR50 Mode



Parameter	Symbol	Minimum	Maximum	Unit	Comments
–	t_{CLK}	20	–	ns	DDR50 mode
–	t_{CR},t_{CF}	–	0.2 × tCLK	ns	t_{CR}, t_{CF} < 4.00 ns (max) @50 MHz, C_{CARD} = 10 pF
Clock duty	–	45	55	%	–

Data Timing



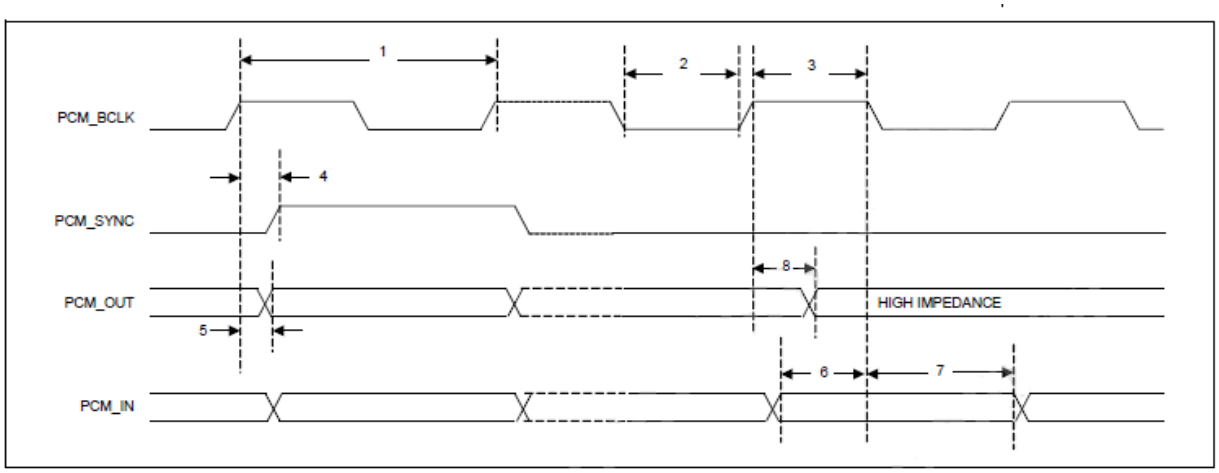
Parameter	Symbol	Minimum	Maximum	Unit	Comments
Input CMD					
Input setup time	t_{ISU}	6	–	ns	C_{CARD} < 10 pF (1 Card)
Input hold time	t_{IH}	0.8	–	ns	C_{CARD} < 10 pF (1 Card)
Output CMD					
Output delay time	t_{ODLY}	–	13.7	ns	C_{CARD} < 30 pF (1 Card)
Output hold time	t_{OH}	1.5	–	ns	C_{CARD} < 15 pF (1 Card)
Input DAT					
Input setup time	t_{ISU2x}	3	–	ns	C_{CARD} < 10 pF (1 Card)
Input hold time	t_{IH2x}	0.8	–	ns	C_{CARD} < 10 pF (1 Card)
Output DAT					
Output delay time	t_{ODLY2x}	–	7.5	ns	C_{CARD} < 25 pF (1 Card)
Output hold time	t_{ODLY2x}	1.5	–	ns	C_{CARD} < 15 pF (1 Card)

8.3 PCM Interface Description

The PCM Interface on the AP5812 can connect to linear PCM Codec devices in master or slave mode. In master mode, the AP5812 generates the PCM_CLK and PCM_SYNC signals, and in slave mode, these signals are provided by another master on the PCM interface and are inputs to the AP5812.The configuration of the PCM interface may be adjusted by the host through the use of vendor-specific HCI commands.

Short Frame Sync, Master Modem

PCM Timing Diagram (Short Frame Sync, Master Mode)

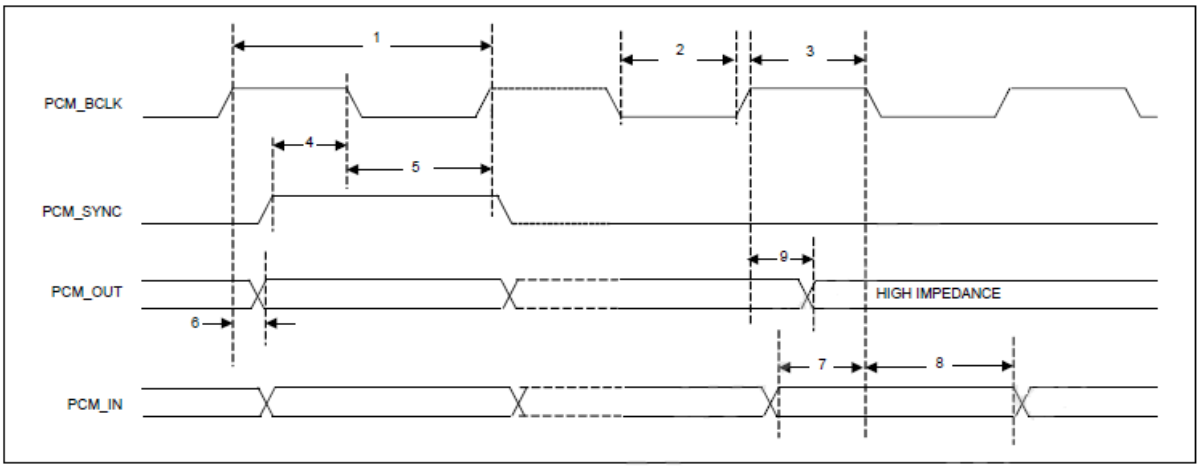


PCM Interface Timing Specifications (Short Frame Sync, Master Mode)

Reference	Characteristics	Minimum	Typical	Maximum	Unit
1	PCM bit clock frequency		–	12	MHz
2	PCM bit clock low	41	–	–	ns
3	PCM bit clock high	41	–	–	ns
4	PCM_SYNC delay	0	–	25	ns
5	PCM_OUT delay	0	–	25	ns
6	PCM_IN setup	8	–	–	ns
7	PCM_IN hold	8	–	–	ns
8	Delay from rising edge of PCM_BCLK during last bit period to PCM_OUT becoming high impedance	0	–	25	ns

Short Frame Sync, Slave Mode

PCM Timing Diagram (Short Frame Sync, Slave Mode)

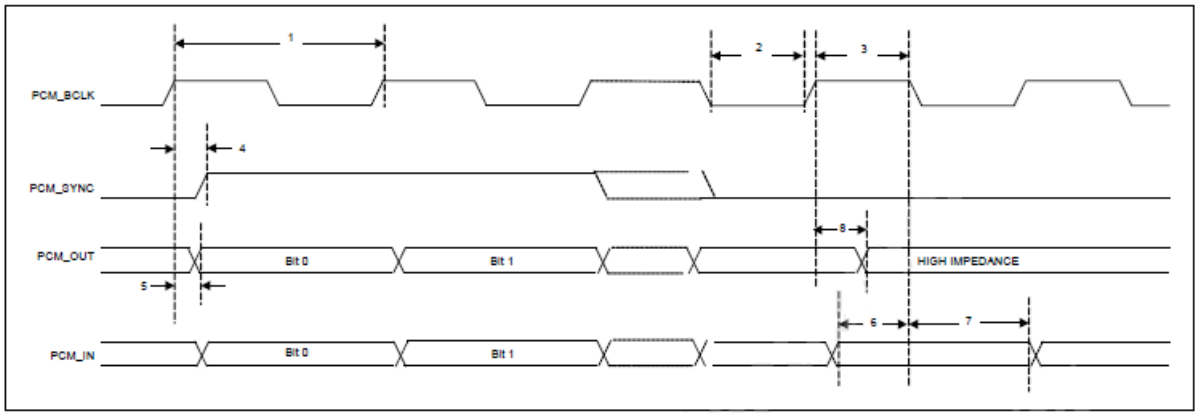


PCM Interface Timing Specifications (Short Frame Sync, Slave Mode)

Reference	*Characteristics*	*Minimum*	*Typical*	*Maximum*	*Unit*
1	PCM bit clock frequency	–	–	12	MHz
2	PCM bit clock low	41	–	–	ns
3	PCM bit clock high	41	–	–	ns
4	PCM_SYNC setup	8	–	–	ns
5	PCM_SYNC hold	8	–	–	ns
6	PCM_OUT delay	0	–	25	ns
7	PCM_IN setup	8	–	–	ns
8	PCM_IN hold	8	–	–	ns
9	Delay from rising edge of PCM_BCLK during last bit period to PCM_OUT becoming high impedance	0	–	25	ns

Long Frame Sync, Master Mode

PCM Timing Diagram (Long Frame Sync, Master Mode)

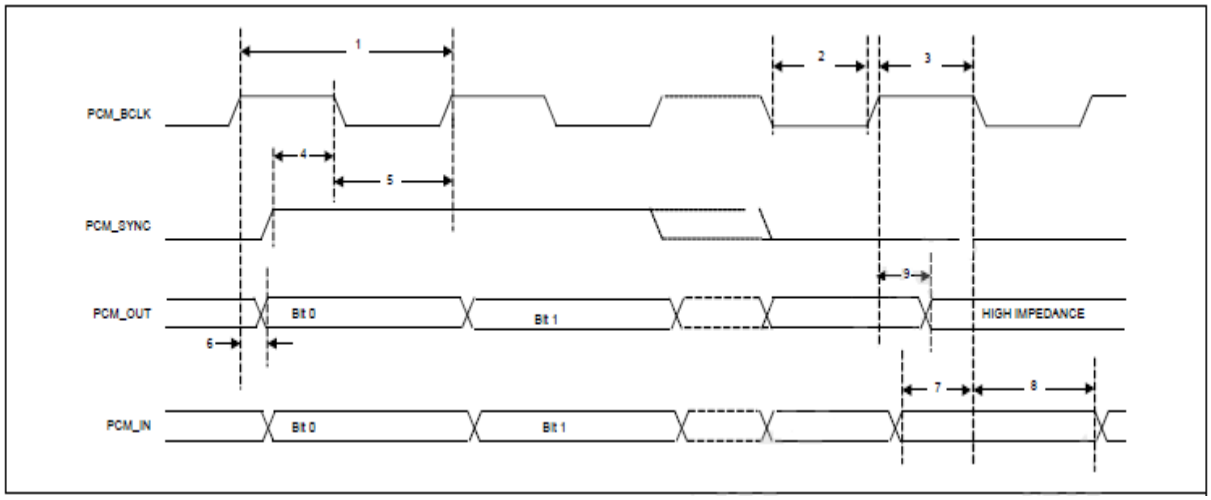


PCM Interface Timing Specifications (Long Frame Sync, Master Mode)

Reference	*Characteristics*	*Minimum*	*Typical*	*Maximum*	*Unit*
1	PCM bit clock frequency	–	–	12	MHz
2	PCM bit clock low	41	–	–	ns
3	PCM bit clock high	41	–	–	ns
4	PCM_SYNC delay	0	–	25	ns
5	PCM_OUT delay	0	–	25	ns
6	PCM_IN setup	8	–	–	ns
7	PCM_IN hold	8	–	–	ns
8	Delay from rising edge of PCM_BCLK during last bit period to PCM_OUT becoming high impedance	0	–	25	ns

Long Frame Sync, Slave Mode

PCM Timing Diagram (Long Frame Sync, Slave Mode)

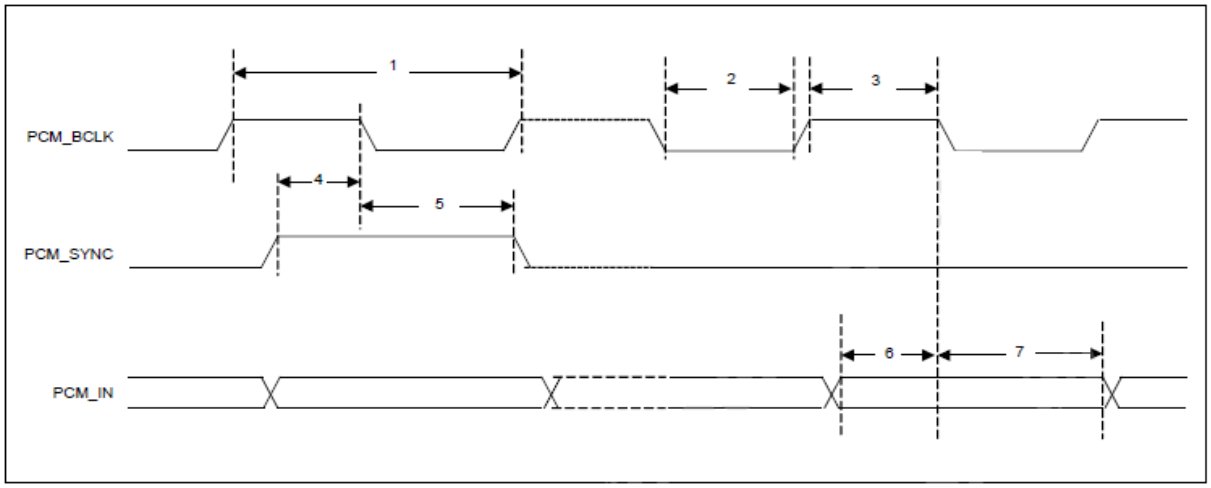


PCM Interface Timing Specifications (Long Frame Sync, Slave Mode)

Reference	*Characteristics*	*Minimum*	*Typical*	*Maximum*	*Unit*
1	PCM bit clock frequency	–	–	12	MHz
2	PCM bit clock low	41	–	–	ns
3	PCM bit clock high	41	–	–	ns
4	PCM_SYNC setup	8	–	–	ns
5	PCM_SYNC hold	8	–	–	ns
6	PCM_OUT delay	0	–	25	ns
7	PCM_IN setup	8	–	–	ns
8	PCM_IN hold	8	–	–	ns
9	Delay from rising edge of PCM_BCLK during last bit period to PCM_OUT becoming high impedance	0	–	25	ns

Short Frame Sync, Burst Mode

PCM Burst Mode Timing (Receive Only, Short Frame Sync)

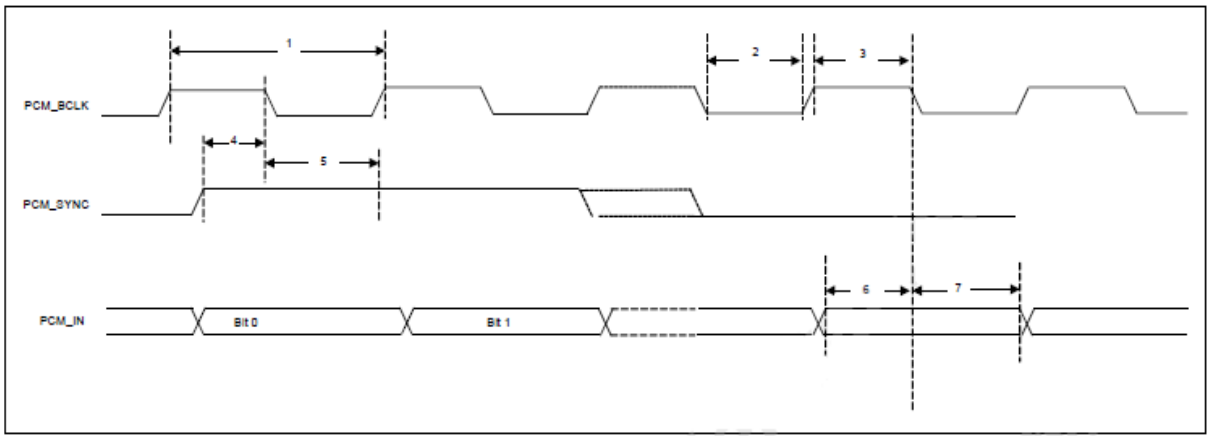


PCM Burst Mode (Receive Only, Short Frame Sync)

Reference	Characteristics	Minimum	Typical	Maximum	Unit
1	PCM bit clock frequency	–	–	24	MHz
2	PCM bit clock low	20.8	–	–	ns
3	PCM bit clock high	20.8	–	–	ns
4	PCM_SYNC setup	8	–	–	ns
5	PCM_SYNC hold	8	–	–	ns
6	PCM_IN setup	8	–	–	ns
7	PCM_IN hold	8	–	–	ns

Long Frame Sync, Burst Mode

PCM Burst Mode Timing (Receive Only, Long Frame Sync)



PCM Burst Mode (Receive Only, Long Frame Sync)

Reference	Characteristics	Minimum	Typical	Maximum	Unit
1	PCM bit clock frequency	–	–	24	MHz
2	PCM bit clock low	20.8	–	–	ns
3	PCM bit clock high	20.8	–	–	ns
4	PCM_SYNC setup	8	–	–	ns
5	PCM_SYNC hold	8	–	–	ns
6	PCM_IN setup	8	–	–	ns
7	PCM_IN hold	8	–	–	ns

8.4 UART Interface Description

The UART is a standard 4-wire interface (RX, TX, RTS, and CTS) with adjustable baud rates from 9600 bps to 4.0 Mbps. The interface features an automatic baud rate detection capability that returns a baud rate selection. Alternatively, the baud rate may be selected through a vendor-specific UART HCI command.

UART has a 1040-byte receive FIFO and a 1040-byte transmit FIFO to support EDR. Access to the FIFOs is conducted through the AHB interface through either DMA or the CPU. The UART supports the Bluetooth 5.0 UART HCI specification: H4, a custom Extended H4, and H5. The default baud rate is 115.2 Kbaud.

The UART supports the 3-wire H5 UART transport, as described in the Bluetooth specification (Three-wire UART Transport Layer). Compared to H4, the H5 UART transport reduces the number of signal lines required by eliminating the CTS and RTS signals.

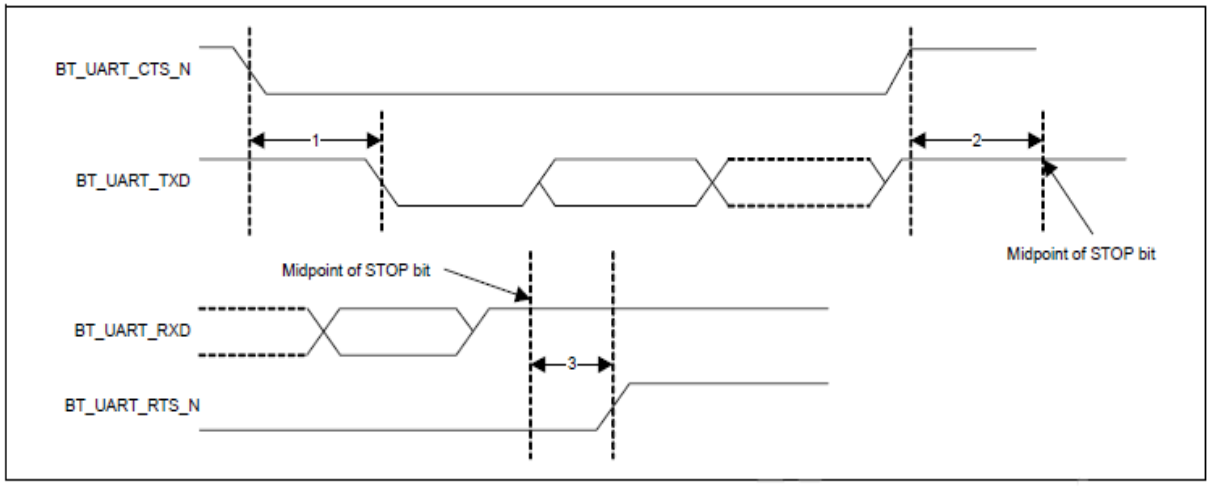
The UART can perform XON/XOFF flow control and includes hardware support for the Serial Line Input Protocol (SLIP). It can also perform wake-on activity. For example, activity on the RX or CTS inputs can wake the chip from a sleep state.

Normally, the UART baud rate is set by a configuration record downloaded after device reset, or by automatic baud rate detection, and the host does not need to adjust the baud rate. Support for changing the baud rate during normal HCI UART operation is included through a vendor-specific command that allows the host to adjust the contents of the baud rate registers. The UARTs operate correctly with the host UART as long as the combined baud rate error of the two devices is within ±2%.

Example of Common Baud Rates

Desired Rate	Actual Rate	Error (%)
4000000	4000000	0.00
3692000	3692308	0.01
3000000	3000000	0.00
2000000	2000000	0.00
1500000	1500000	0.00
1444444	1454544	0.70
921600	923077	0.16
460800	461538	0.16
230400	230796	0.17
115200	115385	0.16
57600	57692	0.16
38400	38400	0.00
28800	28846	0.16
19200	19200	0.00
14400	14423	0.16
9600	9600	0.00

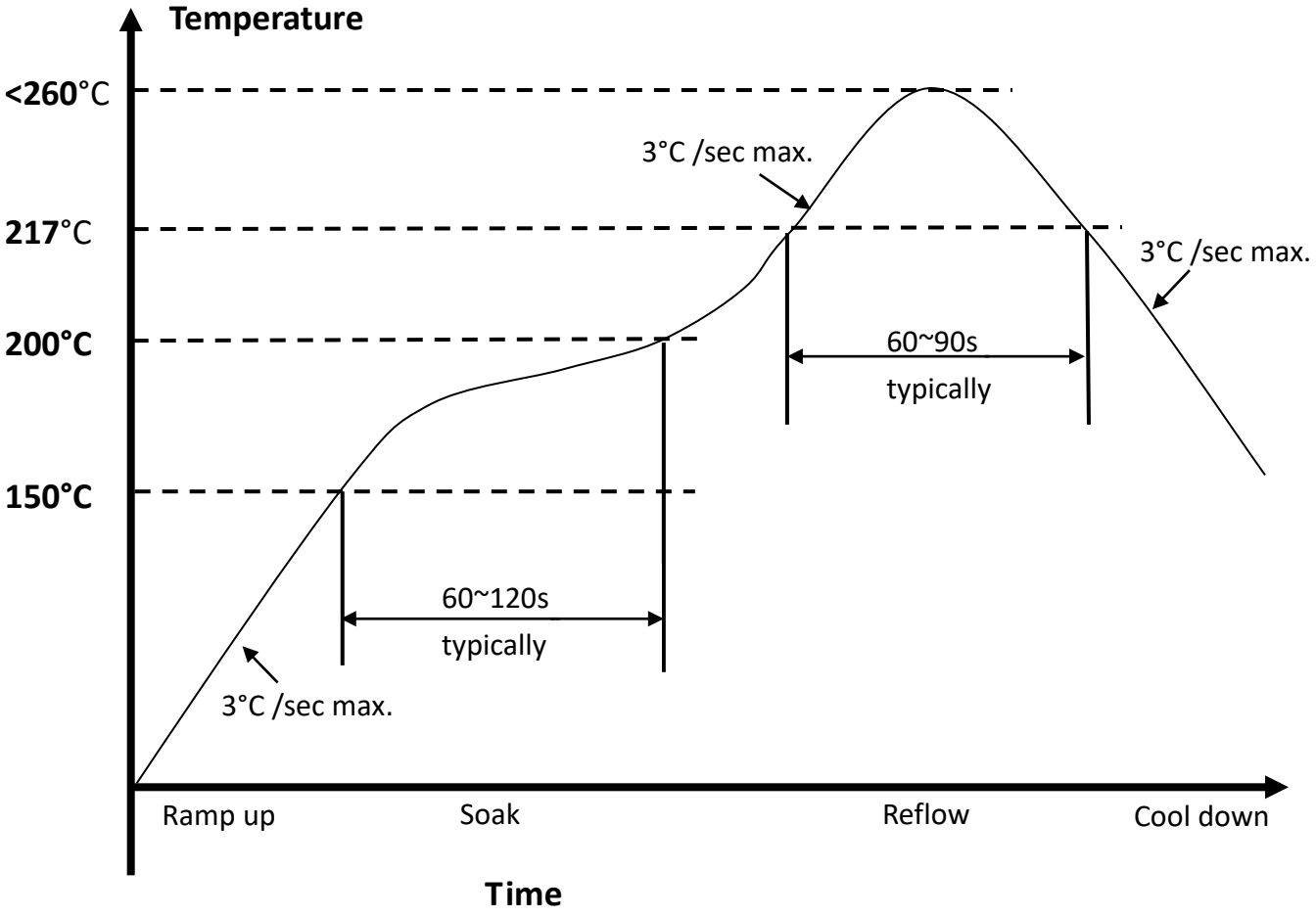
UART Timing



UART Timing Specifications

Ref	Characteristics	Min.	Typ.	Max.	Unit
1	Delay time, BT_UART_CTS_N low to BT_UART_TXD valid	–	–	1.5	Bit periods
2	Setup time, BT_UART_CTS_N high before midpoint of stop bit	–	–	0.5	Bit periods
3	Delay time, midpoint of stop bit to BT_UART_RTS_N high	–	–	0.5	Bit periods

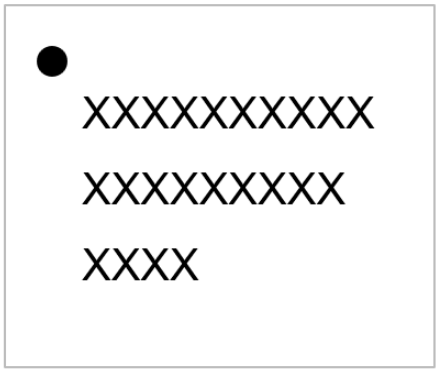
9. Recommended Reflow Profile



1. Referred to IPC/JEDEC standard
2. Peak Temperature : <260°C(Time within 5°C of actual Peak Temperature 20-40 seconds)
3. Cycle of Reflow : 2 times max.
4. Adding Nitrogen (N2) to implement 2000ppm or less of oxygen concentration during reflow process is recommended.
5. If the shelf time is exceeded, be sure baking step to remove the moisture from the component

10. Package Information

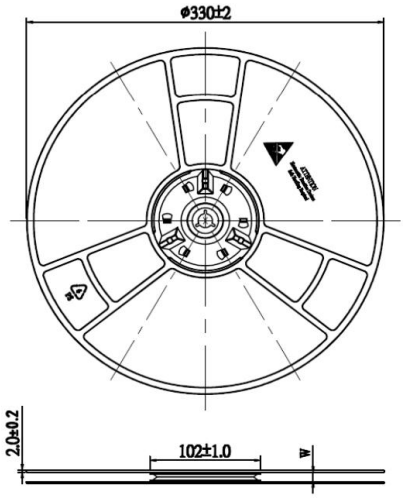
10.1 Marking



Rows	Content	Note
Row 1	Pin1 a circular point	Pin1
Row 2	XXXXXXXX	Model Name
Row 3	XXXXXXXX or XXXXXXXXX (8 digitals or 9 digitals)	Lot Code
Row 4	YYWW	Date Code

10.2 Tape & Reel Data

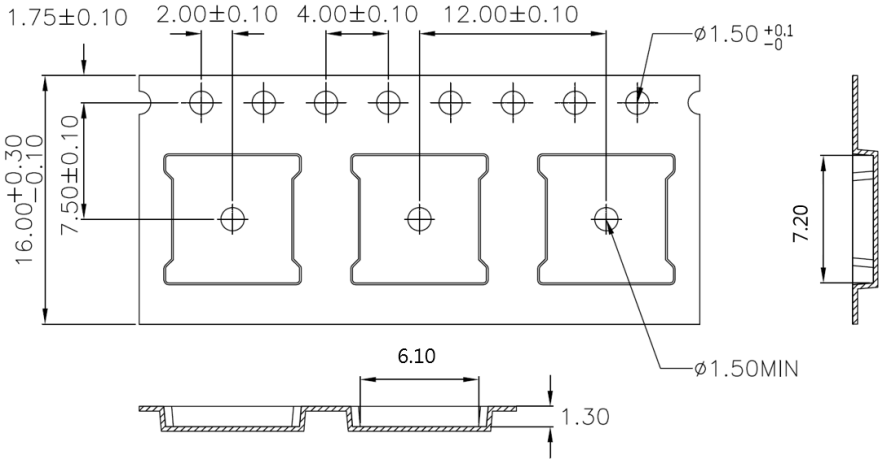
Reel

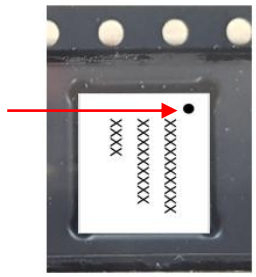
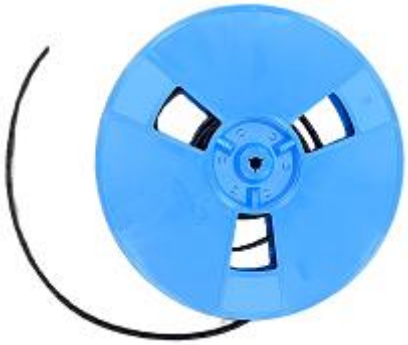


(unit :mm)

Carrier tape (unit :mm)

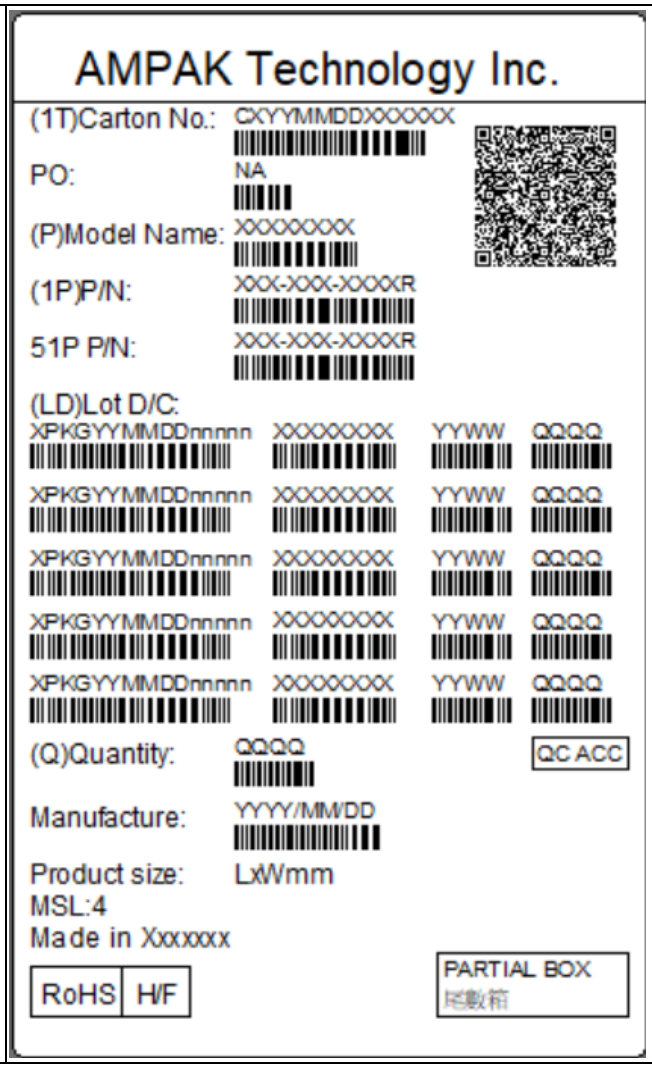
10.3 Tape & Reel Packing



Items	Photo	Description
1	Pin 1 	Pin 1 indicator in carrier tape
2		13" W16.0mm Reel
3		Humidity Indicator Card & Desiccant inside

4		MSL Caution label on top side of Al bag
5		Anti-static and humidity notice on top side of Al bag
6	Caution This bag contains MOISTURE-SENSITIVE DEVICES LEVEL 4 If blank,see adjacent bar code label 1. Calculated shelf life in sealed bag:12months at<40℃and <90% relative humidity(RH) 2. Peak package body temperature:250℃ If blank,see adjacent bar code label 3. After bag is opened,devices that will be subjected to reflow solder or other high temperature process must be a) Mounted within:72 hours of factory conditions If blank,see adjacent bar code label ≤30℃/60% RH,or b) Stored per J-STD-033 4. Devices require bake,before mounting,if: a) Humidity Indicator Card reads>10% for level 2a-5a devices or>60% for level 2 devices when read at 23±5℃ b) 3a or 3b are not met. 5.If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure. Bag Seal Date: If blank,see adjacent bar code label Note:Level and body temperature defined by IPC/JEDEC J-STD-020	MSL Level / Storage Condition
7		1 reel per inner box (Box) Quantity:2000pcs/reel

8	(1T)PKG S/N: XPKGYYMMDDnnnnn PO: NA (P)Model Name: XXXXXXXX (1P)P/N: XXX-XXX-XXXXR 51P P/N: XXX-XXX-XXXXR (L)Lot Code: XXXXXXXX (D)Date Code: YYWW (Q)Quantity: QQQQ Product size: LxWmm MSL:4 Made in Xxxxxx RoHS H/F QC ACC PARTIAL BOX 尾數箱	Inner box (Box) label (Reel label/Al Bag label/Box label) The label content includes barcode and QR CODE
9		5 inner boxes per outer box (Carton) Quantity: 10000pcs/outer box (Carton)
10		Outer box (Carton) Quantity: 10000pcs/outer box (Carton)

11		Outer box (Carton) label The label content includes barcode and QR CODE